

RESIN COMPOSITION FOR ENCAPSULATING SEMICONDUCTOR AND SEMICONDUCTOR DEVICE

ABSTRACT

Disclosed is a resin composition for encapsulating a semiconductor containing an epoxy resin (A), a curing agent (B),
5 and an inorganic filler (C), wherein the epoxy resin (A) includes an epoxy resin (A1) having a predetermined structure, and the curing agent (B) includes a phenol resin (B1) having a predetermined structure, wherein the content of a c=1 component included in the total amount of the phenol resin (B1) is not less
10 than 40% in terms of area percentage and the content of a C $\geq$ 4 component is not more than 20% in terms of area percentage, as measured by the area method of gel permeation chromatography. Also disclosed is a semiconductor device obtained by encapsulating a semiconductor element with a cured product of the resin composition
15 for encapsulating a semiconductor.

No Suitable Figure